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General Information

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	36 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.6mm +/-0.15mm
S	1.5mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	8000

Specifications

Capacitance	240 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2,400 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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